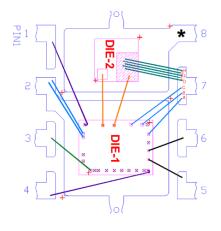
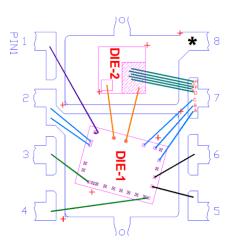


# Final Product/Process Change Notification Document #: FPCN22099X Issue Date: 19 December 2017

| Title of Change:  | Wire Bond Layout Change at OSPI Carmona for LV5980MC-AH (SOIC8).   |  |  |
|---|--|--|--|
| Proposed first ship date:   | 26 March 2018  |  |  |
| Contact information:  | Contact your local ON Semiconductor Sales Office or <hidekazu.inoue@onsemi.com></hidekazu.inoue@onsemi.com>  |  |  |
| Samples:  | Contact your local ON Semiconductor Sales Office   |  |  |
| Additional Reliability Data:  | Contact your local ON Semiconductor Sales Office or <satoru.fujinuma@onsemi.com>.</satoru.fujinuma@onsemi.com>   |  |  |
| Type of notification:   | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com> |  |  |
| Change Part Identification:   | Affected products will be identified with date code.   |  |  |
| Change category:  | ☐ Wafer Fab Change ☐ Assembly Change   | e Test Change Dother   |  |
| Change Sub-Category(s):  ☐ Manufacturing Site Change/Addition ☐ Material Change ☐ Product specific change |  | ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other: |  |
| Sites Affected:   | ON Semiconductor Sites:<br>ON Carmona, Philippines   | External Foundry/Subcon Sites: None                                  |  |
| Description and Purpose:  | 1  |  |  |
| This is inform customers of the c   | hange in wire bond lay-out for LV5980MC-AH at C  | DSPI Carmona.  |  |
| Die-1 will be rotated to avoid win  | re short of pin 4.   |  |  |
| BEFORE change descript  | tion (Die1 no-rotated)   | ter change description(Die1 rotated)                                 |  |





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## Final Product/Process Change Notification Document #: FPCN22099X

Issue Date: 19 December 2017

## **Reliability Data Summary:**

#### QV DEVICE NAME LV5980MC-AH PACKAGE SOIC08

| Test  | Specification       | Condition                         | Interval | Results |
|-------|---------------------|-----------------------------------|----------|---------|
| HTSL  | JESD22-A103         | Ta= 150°C                         | 1000 hrs | 0/231   |
| TC    | JESD22-A104         | Ta= -65°C to +150°C               | 500cyc   | 0/231   |
| uHAST | JESD22-A118         | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs   | 0/231   |
| PC    | J-STD-020 JESD-A113 | MSL =3 @ 260 °C                   |          | 0/462   |

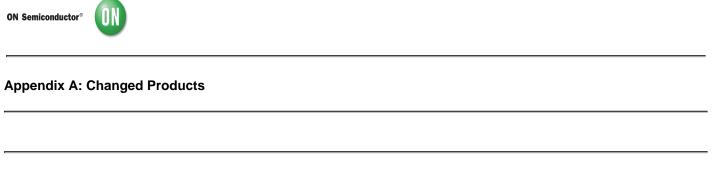
## **Electrical Characteristic Summary:**

There is no change in the electrical performance. Datasheet specifications remain unchanged.

#### **List of Affected Standard Parts:**

| Part Number | Qualification Vehicle |  |
|-------------|-----------------------|--|
| LV5980MC-AH | LV5980MC-AH           |  |

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| Product     | Customer Part Number | Qualification Vehicle |
|-------------|----------------------|-----------------------|
| LV5980MC-AH |                      | LV5980MC-AH           |
|             |                      |                       |